低功耗、3.3V 电源全双工 RS-485 驱动器/接收器

查询样品：SN65HVD37

特性

- 低电流待机模式：**<1 µA** 典型值
- 工作静态电流 **< 1 mA**
- 为避免噪声干扰的高接收器迟滞（典型值 **60mV**）
- **1/8** 单位负载 **(**在总线上多达 **256** 个结点**)**
- 超过 **15 kV HBM** 的总线引脚 **ESD** 保护
- 用于高达 **20 Mbps** 信号传输速度的驱动器输出转换时间优化
- 用于带电插入应用的无波形干扰的加电和断电保护
- **5V-**容错逻辑输入
- 总线空闲、打开和短路故障安全
- 驱动器电流限制和热关断
- 全面符合所有**TIA-485-A** 规范

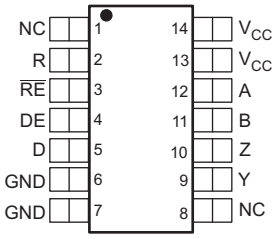
应用

- 电信设备
- 工业自动化
- 过程自动化
- 楼宇自动化
- 销售点（**POS**）终端
- 是 **ADM3076, ADM3491, LTC2852, MAX3491** 和 **SP3491** 的改良替代产品

说明

SN65HVD37 将一个强健的差分驱动器和一个具有高抗噪性的接收器结合在一起以满足要求严格的工业应用的需要。 这个驱动器的差分输出和接收器的差分输入是分离的引脚，这样的话就形成了一个用于全双工（四线制）通讯的总线端口。 这个驱动器和接收器可以独立启用并特有一个宽泛的共模电压范围，这使得此设备适合在长线缆上运行的多点应用。 SN65HVD37 额定工作温度范围为 -40ºC 至 85 ºC。

D PACKAGE (TOP VIEW)



NC - No internal connection

LOGIC DIAGRAM (POSITIVE LOGIC)

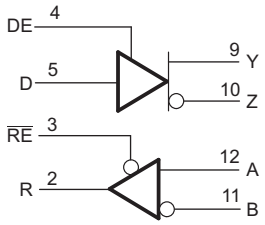




图 **1.** 为避免噪声干扰的**60 mV** 接收器迟滞

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of the Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

ABSOLUTE MAXIMUM RATINGS(1)

			VALUE/UNITS
V_{CC}	Supply voltage		–0.5 V to 7 V
	Voltage range at A, B, Y, Z pins		–13 V to 13 V
	Input voltage range at any logic pin		–0.3 V to 5.7 V
	Voltage range, transient pulse, A, B, Y, Z, through 100Ω		–25 V to 25 V
	Receiver output current		–24 mA to 24 mA
T_J	Junction temperature		170°C
	Continuous total power dissipation		(see Thermal Table)
	IEC 60749-26 ESD	(Human Body Model), bus terminals and GND	±16 kV
	JEDEC Standard 22	Test Method A114 (Human Body Model), all pins	±5 kV
		Test Method C101 (Charged Device Model), all pins	±1.5 kV
	JEDEC Standard 22	Test Method A115 (Machine Model), all pins	±150 V

(1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

THERMAL INFORMATION

THERMAL METRIC(1)		SN65HVD37	UNITS
		D	
		14 PINS	
θ_{JA}	Junction-to-ambient thermal resistance	79.3	°C/W
θ_{JCtop}	Junction-to-case (top) thermal resistance	44.8	
θ_{JB}	Junction-to-board thermal resistance	33.5	
ψ_{JT}	Junction-to-top characterization parameter	13.3	
ψ_{JB}	Junction-to-board characterization parameter	33.3	

(1) For more information about traditional and new thermal metrics, see the *IC Package Thermal Metrics* application report, SPRA953.

RECOMMENDED OPERATING CONDITIONS

			MIN	NOM	MAX	UNIT
V_{CC}	Supply voltage(1)		3	3.3	3.6	V
V_I	Input voltage at any bus terminal (separately or common mode)(2)		–7		12	V
V_{IH}	High-level input voltage (Driver, driver enable, and receiver enable inputs)		2		VCC	V
V_{IL}	Low-level input voltage (Driver, driver enable, and receiver enable inputs)		0		0.8	V
V_{ID}	Differential input voltage		–12		12	V
I_O	Output current	Driver	–60		60	mA
		Receiver	–8		8	
R_L	Differential load resistance		54	60		Ω
C_L	Differential load capacitance			50		pF
	Signaling rate	HVD37			20	Mbps
T_A	Operating free-air temperature (See application section for thermal information)		–40		85	°C
T_J	Junction Temperature		–40		150	°C

(1) Both pins 13 and 14 should be connected to the supply voltage; both pins 6 and 7 should be connected to ground.
(2) The algebraic convention, in which the least positive (most negative) limit is designated as minimum is used in this data sheet.

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ELECTRICAL CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
$\|V_{OD}\|$	Driver differential output voltage magnitude	See Figure 1, R_L= 60 Ω, V_{CC} ≥ 3.15 V, 375 Ω on each output to –7 V to 12 V		1.5	1.9		V
		R_L = 54 Ω (RS-485)	See Figure 3	1.5	2		V
		R_L = 100 Ω (RS-422), T_J ≥ 25°C, V_{CC} ≥ 3.3 V		2	2.2		V
$\Delta\|V_{OD}\|$	Change in magnitude of driver differential output voltage	R_L = 54 Ω, C_L = 50 pF		–0.1	0	0.1	V
$V_{OC(SS)}$	Steady-state common-mode output voltage	Center of two 27-Ω load resistors, C_L = 50 pF	See Figure 3	1.5	V_{CC} /2	2.5	V
ΔV_{OC}	Change in differential driver output common-mode voltage			–0.1	0	0.1	V
$V_{OC(PP)}$	Peak-to-peak driver common-mode output voltage				400		mV
C_{ID}	Differential input capacitance	A, B			3		pF
C_{OD}	Differential output capacitance	Y, Z			14		pF
V_{IT+}	Positive-going receiver differential input voltage threshold			See (1)	–60	–20	mV
V_{IT-}	Negative-going receiver differential input voltage threshold			–200	–120	See (1)	mV
V_{HYS}	Receiver differential input voltage threshold hysteresis (V_{IT+} – V_{IT-})			30	60		mV
V_{OH}	Receiver high-level output voltage	I_{OH} = –8 mA		2.4	V_{CC}- 0.3		V
V_{OL}	Receiver low-level output voltage	I_{OL} = 8 mA			0.2	0.4	V
I_I	Driver input, driver enable, and receiver enable input current			–2		2	µA
I_{OZ}	Receiver output high-impedance current	V_O = 0 V or V_{CC}, $\overline{RE}$ at V_{CC}		–1		1	µA
I_{OS}	Driver short-circuit output current			–250		250	mA
I_I	Bus input current (disabled driver)	V_{CC} = 3 to 3.6 V or V_{CC} =0 V, DE at 0 V	V_I = 12 V		75	125	µA
			V_I = –7 V	–100	–40		
I_{CC}	Supply current, steady-state, no load (quiescent)	Driver and Receiver enabled	DE = V_{CC}, RE = GND		720	850	µA
		Driver enabled, receiver disabled	DE = V_{CC}, RE = V_{CC}			400	µA
		Driver disabled, receiver enabled	DE = GND, RE = GND			800	µA
		Driver and receiver disabled (standby)	DE = GND, D = open, RE = V_{CC}		0.2	1	µA
	Supply current (dynamic)	See “TYPICAL CHARACTERISTICS” section					

(1) Under any specific conditions, V_{IT+} is assured to be at least V_{HYS} higher than V_{IT-}.

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SWITCHING CHARACTERISTICS

over recommended operating conditions (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
DRIVER							
t_r, t_f	Driver differential output rise/fall time	R_L = 54 Ω, C_L = 50 pF, See Figure 4		3	6	14	ns
t_{PHL}, t_{PLH}	Driver propagation delay				10	20	
$t_{SK(P)}$	Driver pulse skew, $\|t_{PHL} - t_{PLH}\|$					1	
t_{PHZ}, t_{PLZ}	Driver disable time	See Figure 5 and Figure 6			20	50	ns
t_{PZH}, t_{PZL}	Driver enable time	Receiver enabled	See Figure 5 and Figure 6		8	25	ns
		Receiver disabled			2.6	8	µs
RECEIVER							
t_r , t_f	Receiver output rise/fall time	C_L = 15 pF, See Figure 7		2	5	9	ns
t_{PHL}, t_{PLH}	Receiver propagation delay time			40	50	75	ns
$t_{SK(P)}$	Receiver pulse skew, $\|t_{PHL} - t_{PLH}\|$				2	5	ns
t_{PLZ}, t_{PHZ}	Receiver disable time				15	25	ns
$t_{PZL(1)}$, $t_{PZH(1)}$, $t_{PZL(2)}$, $t_{PZH(2)}$	Receiver enable time	Driver enabled, See Figure 8			35	50	ns
		Driver disabled, See Figure 8			3	8	µs

DRIVER FUNCTION TABLE

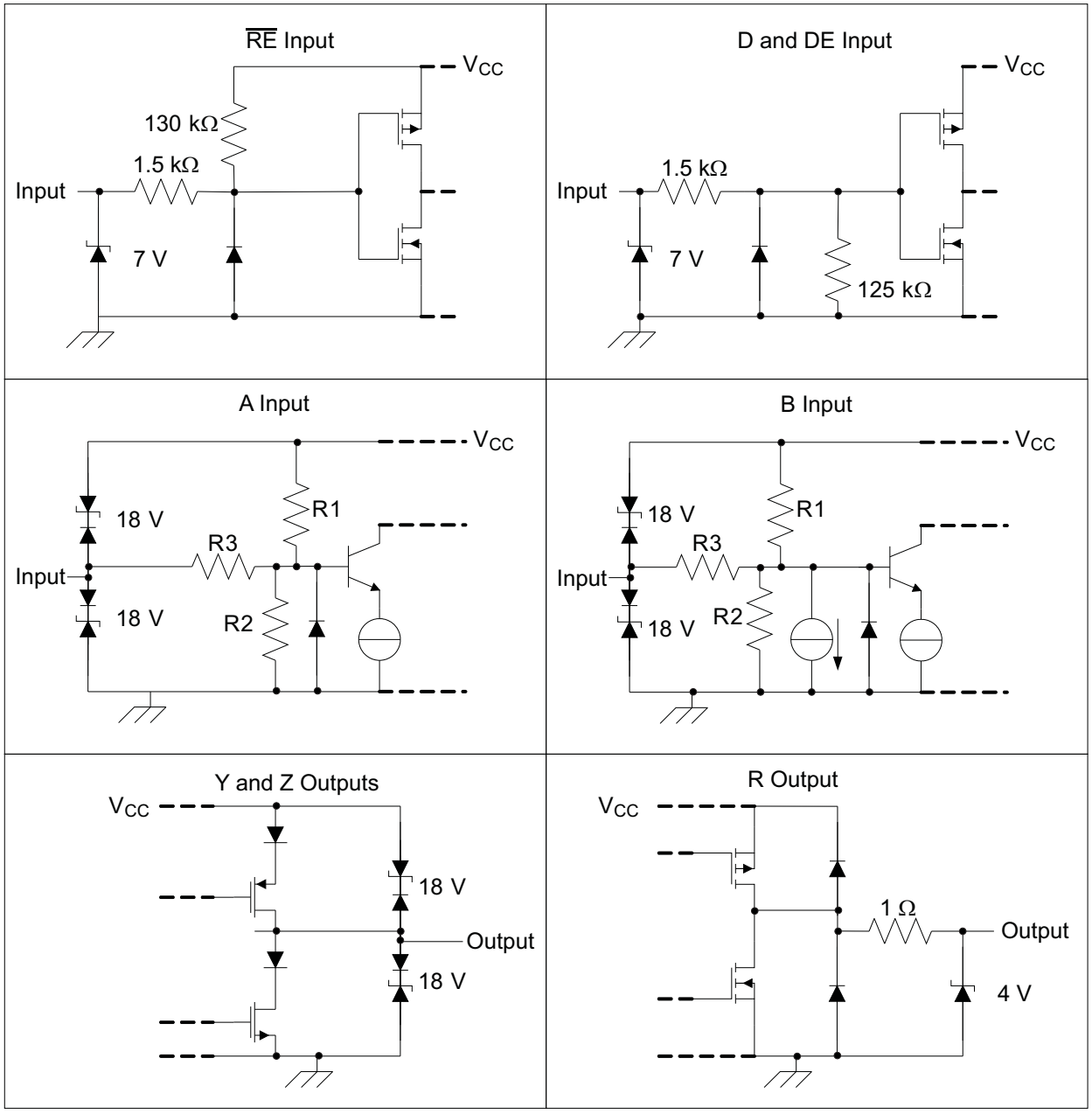
INPUT	ENABLE	OUTPUTS		
D	**DE**	**Y**	**Z**	
H	H	H	L	Actively drive bus High
L	H	L	H	Actively drive bus Low
X	L	Z	Z	Driver disabled
X	OPEN	Z	Z	Driver disabled by default
OPEN	H	H	L	Actively drive bus High by default

RECEIVER FUNCTION TABLE

DIFFERENTIAL INPUT	ENABLE	OUTPUT	
$V_{ID} = V_A - V_B$	**RE**	**R**	
$V_{IT+} < V_{ID}$	L	H	Receive valid bus High
$V_{IT-} < V_{ID} < V_{IT+}$	L	?	Indeterminate bus state
$V_{ID} < V_{IT-}$	L	L	Receive valid bus Low
X	H	Z	Receiver disabled
X	OPEN	Z	Receiver disabled by default
Open-circuit bus	L	H	Fail-safe high output
Short-circuit bus	L	H	Fail-safe high output
Idle (terminated) bus	L	H	Fail-safe high output

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EQUIVALENT INPUT AND OUTPUT SCHEMATIC DIAGRAMS



	R1/R2	R3
SN65HVD37	18 kΩ	190 kΩ

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PARAMETER MEASUREMENT INFORMATION

Input generator rate is 100 kbps, 50% duty cycle, rise and fall times less than 6 nsec, output impedance 50 Ω

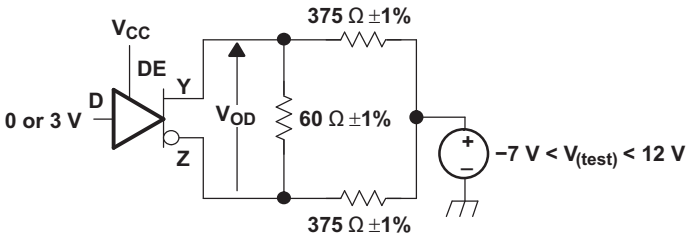


Figure 2. Measurement of Driver Differential Output Voltage With Common-mode Load

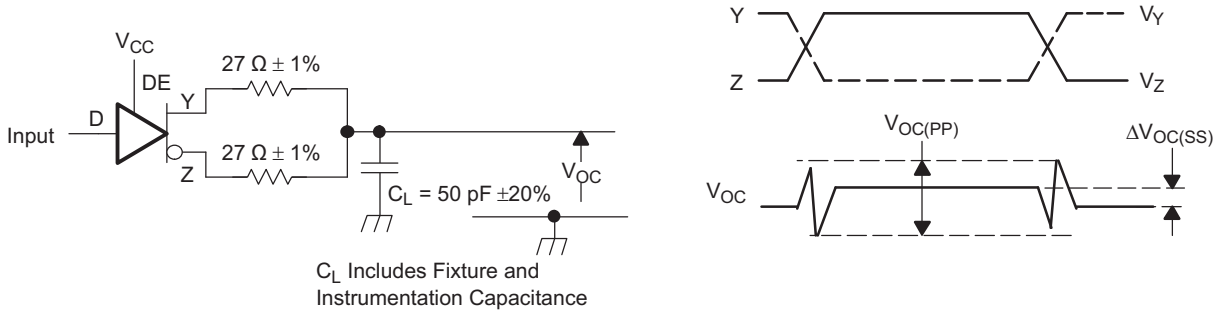


Figure 3. Measurement of Driver Differential and Common-mode Output with RS-485 Load

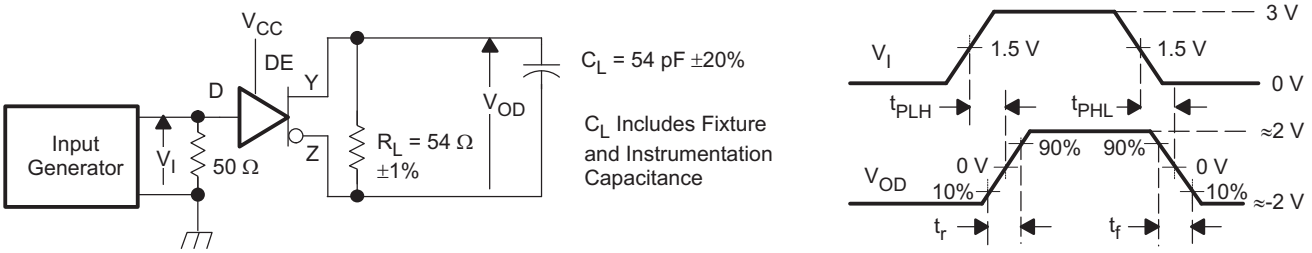
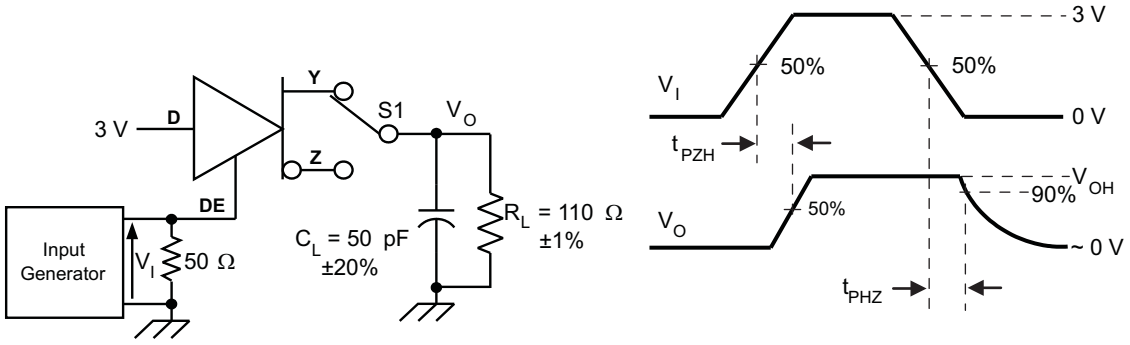


Figure 4. Measurement of Driver Differential Output Rise and Fall Times and Propagation Delays

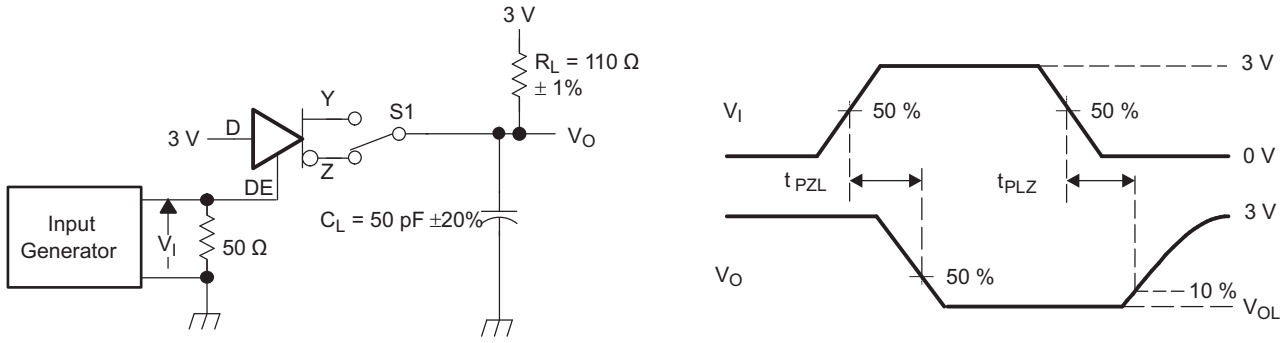


NOTE: D at 3 V to test non-inverting output, D at 0 V to test inverting output.
C_L includes Fixture and Instrumentation Capacitance

Figure 5. Measurement of Driver Enable and Disable Times with Active High Output and Pull-down Load

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PARAMETER MEASUREMENT INFORMATION (continued)



NOTE: D at 0 V to test non-inverting output, D at 3 V to test inverting output.

C_L Includes Fixture and Instrumentation Capacitance

Figure 6. Measurement of Driver Enable and Disable Times with Active Low Output and Pull-up Load

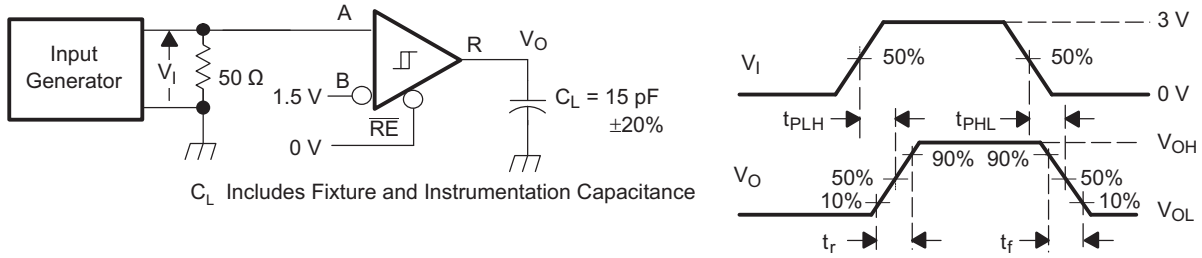


Figure 7. Measurement of Receiver Output Rise and Fall Times and Propagation Delays

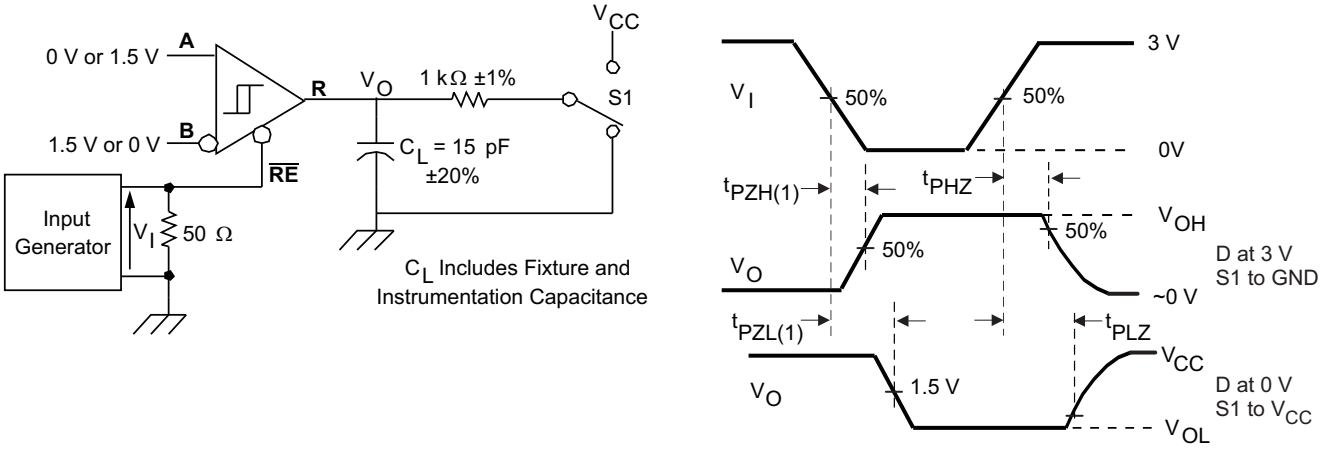


Figure 8. Measurement of Receiver Enable/Disable Times

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TYPICAL CHARACTERISTICS

SUPPLY CURRENT vs SIGNALING RATE

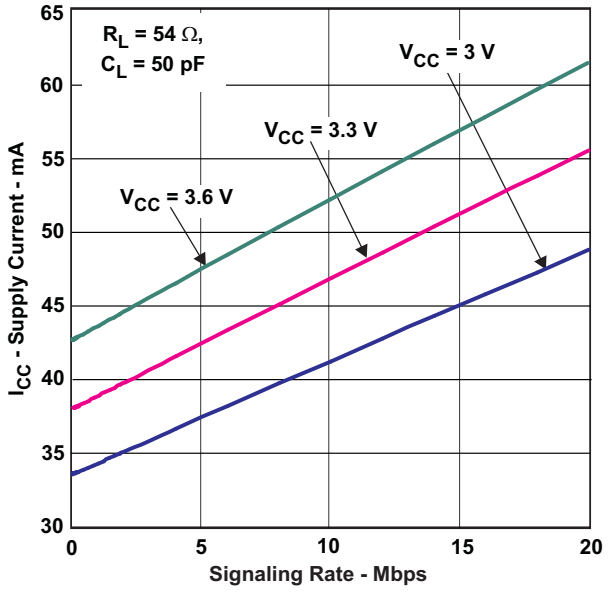


Figure 9.

DIFFERENTIAL OUTPUT VOLTAGE vs DIFFERENTIAL OUTPUT CURRENT

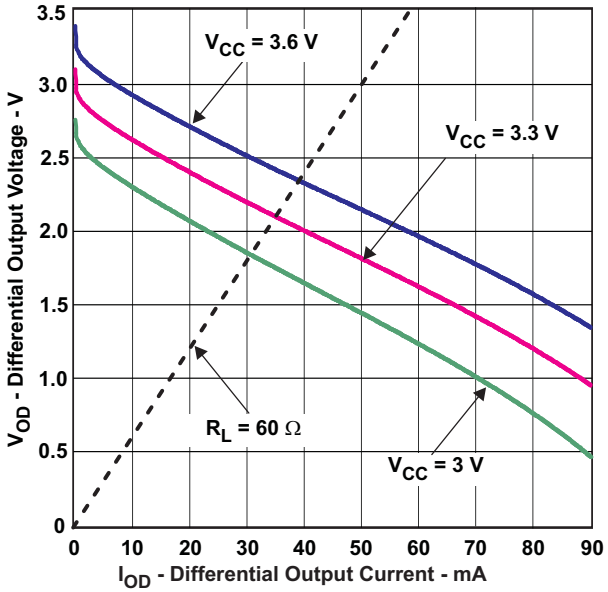


Figure 10.

RECEIVER OUTPUT VOLTAGE vs DIFFERENTIAL INPUT VOLTAGE

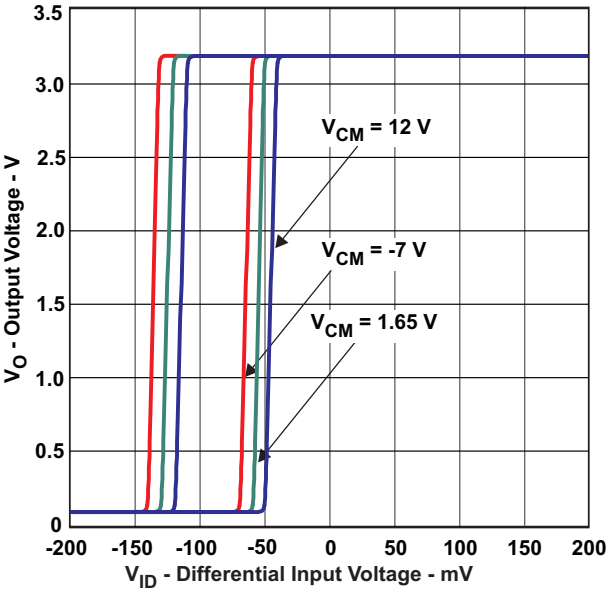


Figure 11.

RECEIVER PROPAGATION DELAY vs FREE-AIR TEMPERATURE

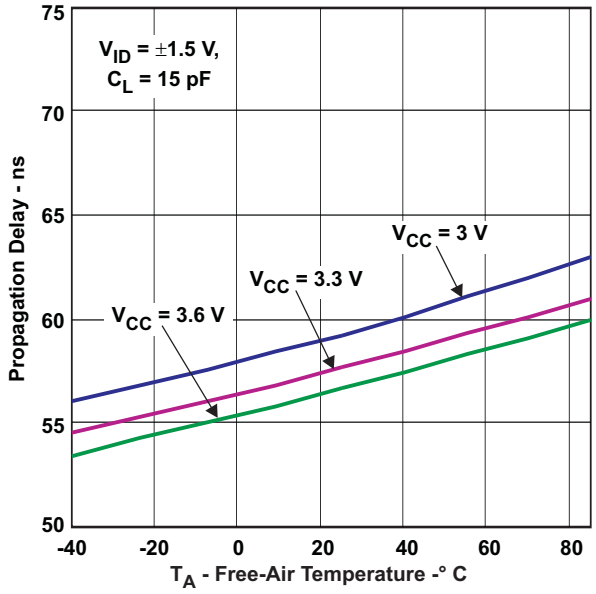


Figure 12.

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TYPICAL CHARACTERISTICS (continued)

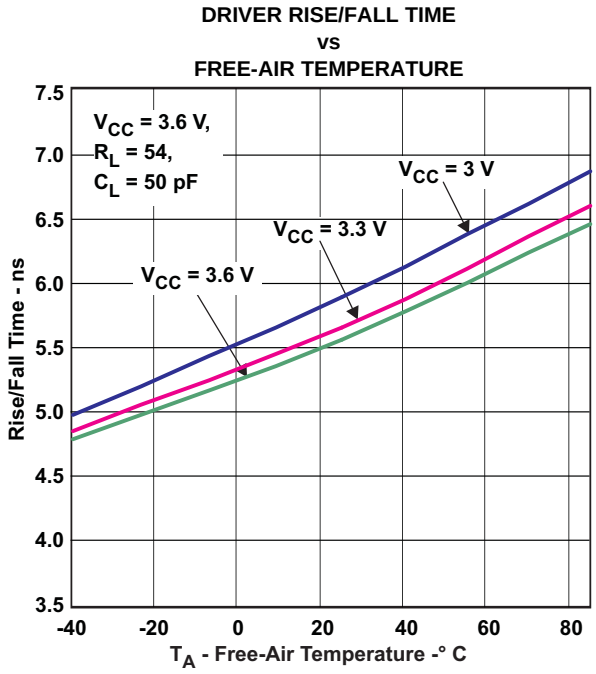


Figure 13.

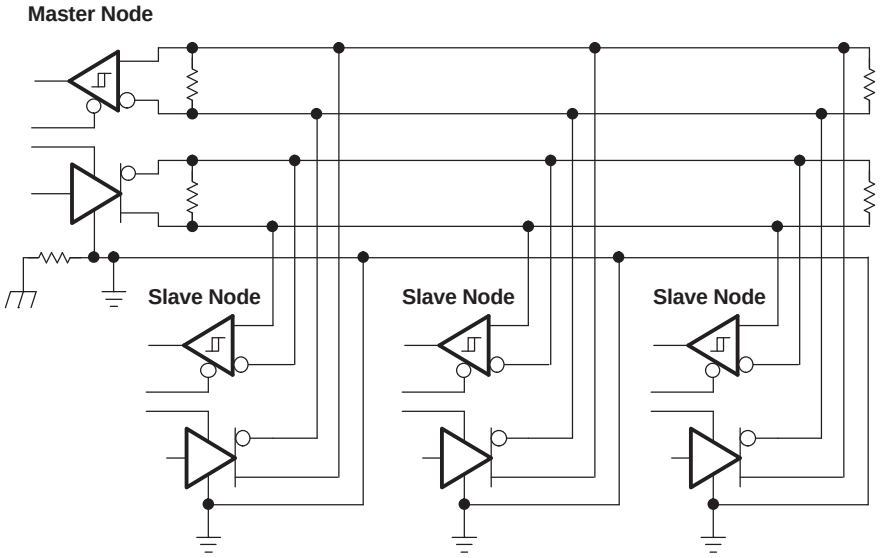


Figure 14. Example Full-Duplex Master/Slave Application Circuit

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APPLICATION INFORMATION

RECEIVER FAILSAFE

The differential receiver is “failsafe” to invalid bus states caused by:

- open bus conditions such as a disconnected connector,
- shorted bus conditions such as cable damage shorting the twisted-pair together,
- or idle bus conditions that occur when no driver on the bus is actively driving.

In any of these cases, the differential receiver outputs a failsafe logic High state, so that the output of the receiver is not indeterminate.

In the HVD37, receiver failsafe is accomplished by offsetting the receiver thresholds so that the “input indeterminate” range does not include zero volts differential. In order to comply with the RS-422 and RS-485 standards, the receiver output must output a High when the differential input V_{ID} is more positive than 200 mV, and must output a Low when the V_{ID} is more negative than -200 mV. The receiver parameters which determine the failsafe performance are V_{IT+} and V_{IT-} and V_{HYS}. In the Electrical Characteristics table, V_{IT-} has a typical value of -120 mV and a minimum (most negative) value of -200 mV, so differential signals more negative than -200 mV will always cause a Low receiver output. Similarly, differential signals more positive than 200 mV will always cause a High receiver output, because the typical value of V_{IT+} is -60mV, and V_{IT+} is never more positive than -20 mV under any conditions of temperature, supply voltage, or common-mode offset.

When the differential input signal is close to zero, it will still be above the V_{IT+} threshold, and the receiver output will be High. Only when the differential input is more negative than V_{IT-} will the receiver output transition to a Low state. So, the noise immunity of the receiver inputs during a bus fault condition includes the receiver hysteresis value V_{HYS} (the separation between V_{IT+} and V_{IT-}) as well as the value of V_{IT+}.

For the HVD37, the typical noise immunity is about 120 mV, which is the negative noise level needed to exceed the V_{IT-} threshold (V_{IT-} TYP = -120 mV). In the worst case, the failsafe noise immunity is never less than 50 mV, which is set by the maximum positive threshold (V_{IT+} MAX = -20mV) plus the minimum hysteresis voltage (V_{HYS} MIN = 30 mV).

HOT-PLUGGING

These devices are designed to operate in “hot swap” or “hot pluggable” applications. Key features for hot-pluggable applications are power-up, power-down glitch free operation, default disabled input/output pins, and receiver failsafe. An internal Power-On Reset circuit keeps the driver outputs in a high-impedance state until the supply voltage has reached a level at which the device will reliably operate. This ensures that no spurious transitions (glitches) will occur on the bus pin outputs as the power supply turns on or turns off.

As shown in the device FUNCTION TABLE, the ENABLE inputs have the feature of default disable on both the driver enable and receiver enable. This ensures that the device will neither drive the bus nor report data on the R pin until the associated controller actively drives the enable pins.

LOW POWER STANDBY MODE

As is customary with RS-485 devices, the receiver output is directly enabled/disabled by $\overline{RE}$, and the driver outputs are directly enabled/disabled by DE.

When both the driver and receiver are disabled, (DE=LO and $\overline{RE}$=HI) the receiver differential comparator stage enters a standby mode for reduced power.

When either the Driver or Receiver is enabled, the receiver differential comparator stage is enabled for fast response to signal changes.

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REVISION HISTORY

Changes from Original (October 2011) to Revision A	Page
• Changed the device From: Product Preview To: Production	1

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PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN65HVD37D	ACTIVE	SOIC	D	14	50	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HVD37	Samples
SN65HVD37DR	ACTIVE	SOIC	D	14	2500	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	HVD37	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".
RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.
Green: TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

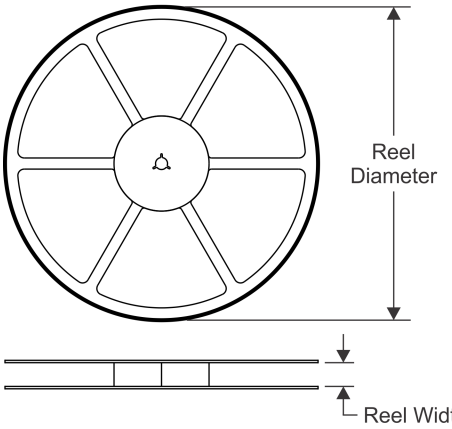
(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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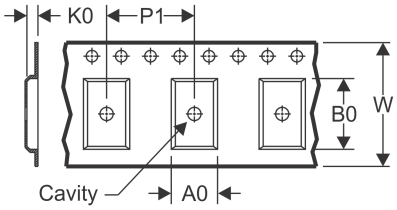
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TAPE AND REEL INFORMATION

REEL DIMENSIONS

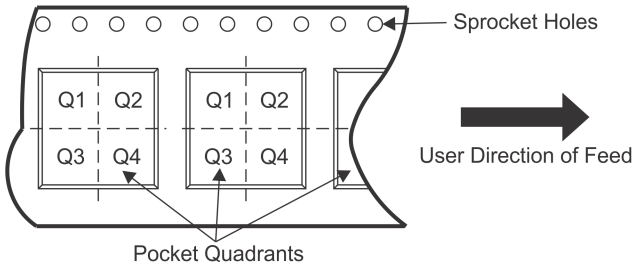


TAPE DIMENSIONS



A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

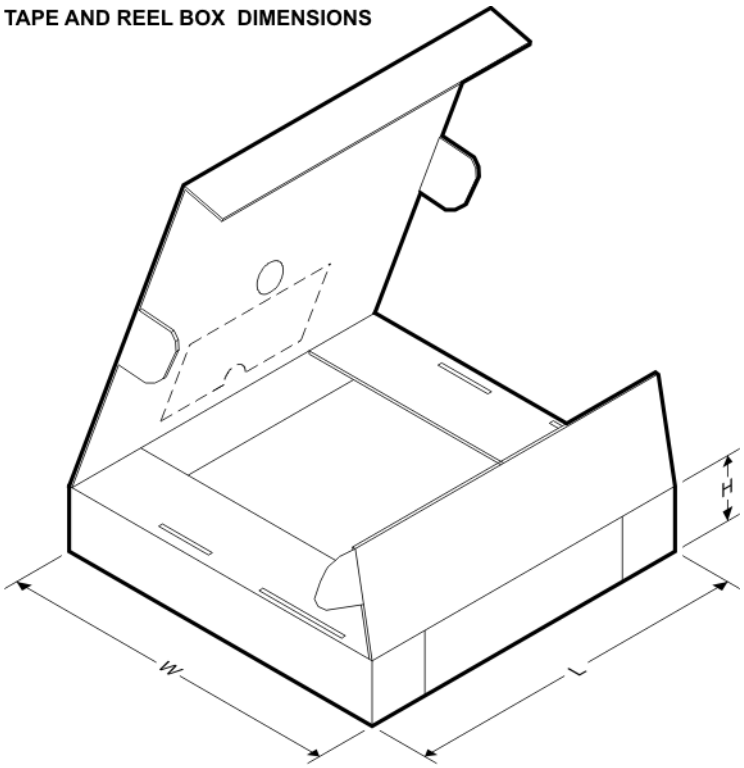
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN65HVD37DR	SOIC	D	14	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1

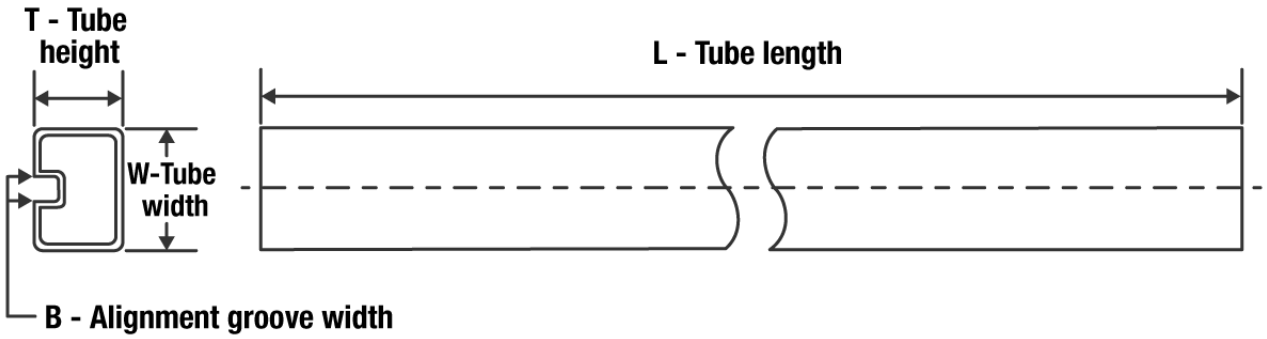
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN65HVD37DR	SOIC	D	14	2500	853.0	449.0	35.0

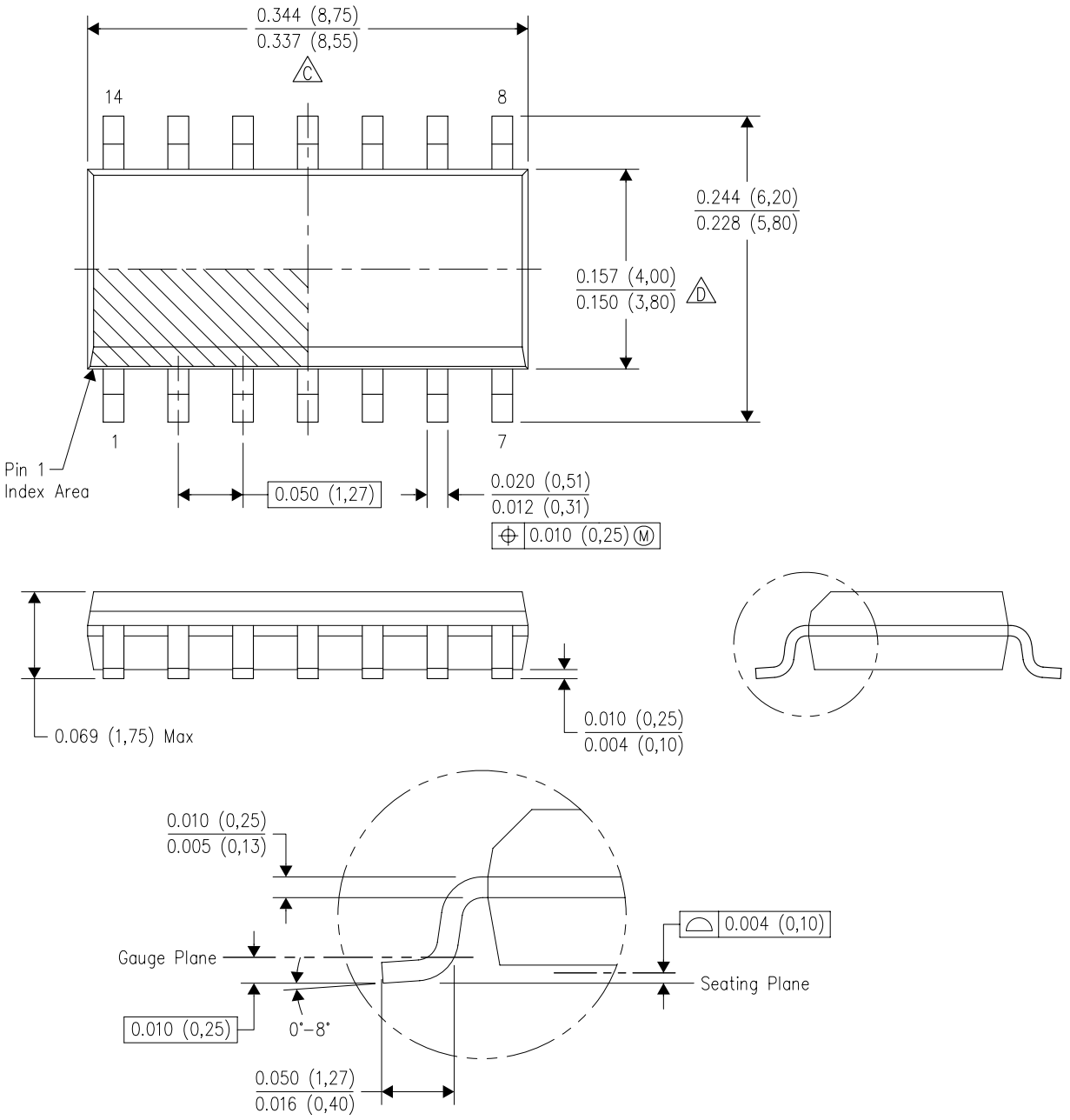
TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN65HVD37D	D	SOIC	14	50	506.6	8	3940	4.32

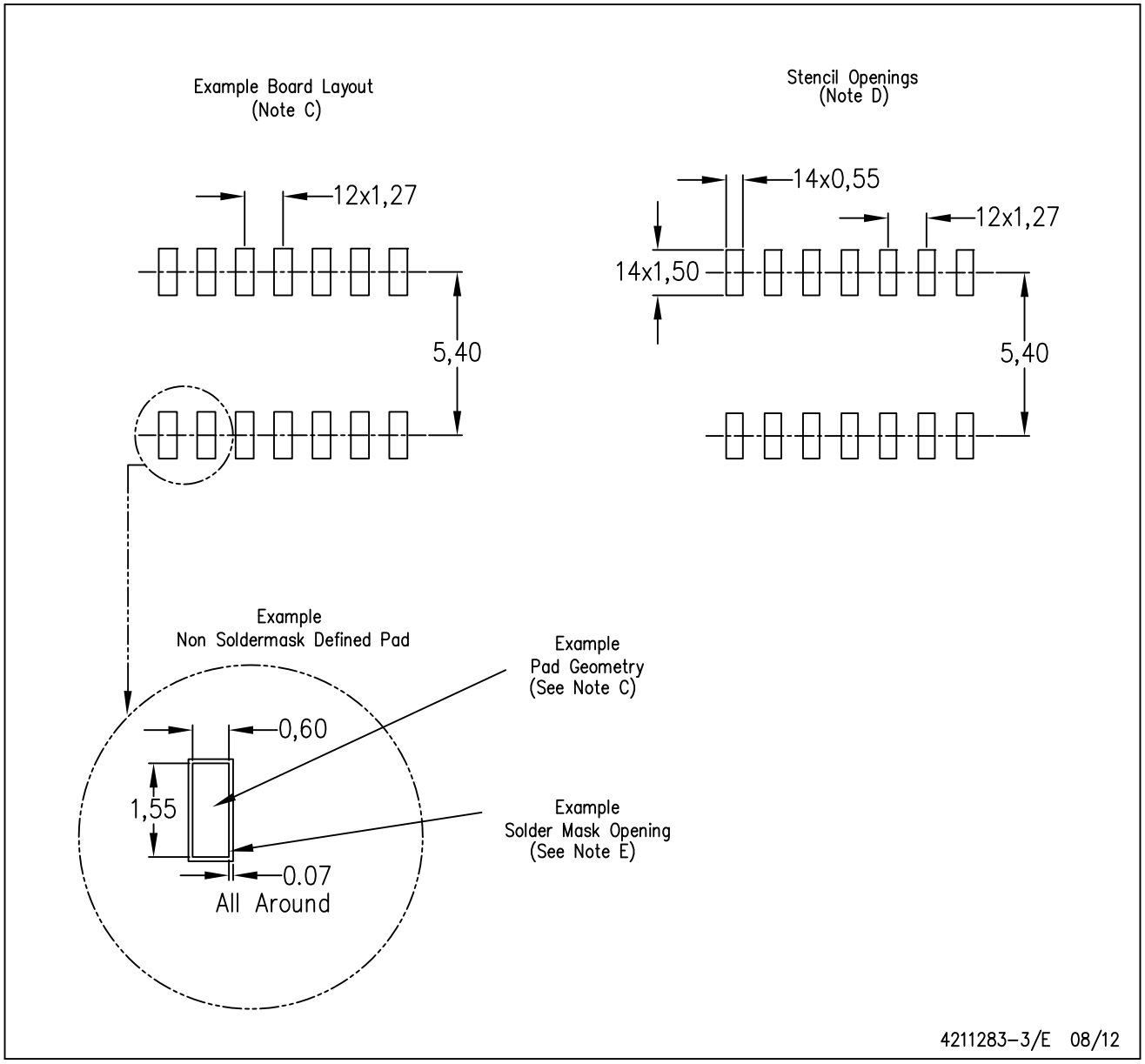
D (R–PDSO–G14) PLASTIC SMALL OUTLINE



4040047–5/M 06/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AB.

D (R–PDSO–G14) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

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